



NSAI
Standards

Irish Standard
I.S. EN 62258-2:2011

Semiconductor die products -- Part 2: Exchange data formats (IEC 62258 -2:2011 (EQV))

I.S. EN 62258-2:2011

Incorporating amendments/corrigenda issued since publication:

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I.S. EN 62258-2:2011

EUROPEAN STANDARD
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EUROPÄISCHE NORM

EN 62258-2

July 2011

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Supersedes EN 62258-2:2005

English version

Semiconductor die products -
Part 2: Exchange data formats
(IEC 62258-2:2011)

Produits de puces de semiconducteurs -
Partie 2: Formats d'échange de données
(CEI 62258-2:2011)

Halbleiter-Chip-Erzeugnisse -
Teil 2: Datenaustausch-Formate
(IEC 62258-2:2011)

This European Standard was approved by CENELEC on 2011-06-29. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Foreword

The text of document 47/2085/FDIS, future edition 2 of IEC 62258-2, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62258-2 on 2011-06-29.

This European Standard supersedes EN 62258-2:2005.

With respect to EN 62258-2:2005, the following parameters have been updated for EN 62258-2:2011:

Subclause	Parameter name
8.2.9	DEVICE_PICTURE_FILE
8.2.10	DEVICE_DATA_FILE
8.4.6	TERMINAL_GROUP
8.4.7	PERMUTABLE
8.5.1	TERMINAL_MATERIAL (was DIE_TERMINAL_MATERIAL)
8.5.2	TERMINAL_MATERIAL_STRUCTURE
8.6.2	MAX_TEMP_TIME
8.7.6	SIMULATOR_simulator_TERM_GROUP
8.8.3	ASSEMBLY
8.9.2	WAFER_THICKNESS
8.9.3	WAFER_THICKNESS_TOLERANCE
8.9.9	WAFER_INK
8.10.4	BUMP_SHAPE
8.10.5	BUMP_SIZE
8.10.6	BUMP_SPECIFICATION_DRAWING
8.10.7	BUMP_ATTACHMENT_METHOD
8.11.4	MPD_MSL_LEVEL
8.11.5	MPD_PACKAGE_DRAWING
8.12.1	QUALITY
8.12.2	TEST
8.13.1	TEXT
8.14.1	PARSE

This standard shall be read in conjunction with EN 62258-1.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN and CENELEC shall not be held responsible for identifying any or all such patent rights.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 2012-03-29
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2014-06-29

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 62258-2:2011 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61360-4	2005	Standard data element types with associated classification scheme for electric components - Part 4: IEC reference collection of standard data element types and component classes	EN 61360-4 + corr. December 2005	2005
IEC 62258-1	-	Semiconductor die products - Part 1: Procurement and use	EN 62258-1	-
ISO 6093	1985	Information processing - Representation of numerical values in character strings for information interchange	-	-
ISO 8601	2004	Data elements and interchange formats - Information interchange - Representation of dates and times	-	-
ISO 10303-21	2002	Industrial automation systems and integration - Product data representation and exchange - Part 21: Implementation methods: Clear text encoding of the exchange structure	-	-
IPC/JEDEC J-STD-033B	2007	Handling, Packing, Shipping and Use of Moisture/Reflow Sensitive Surface Mount Devices	-	-

CONTENTS

FOREWORD.....	5
INTRODUCTION.....	7
1 Scope and object.....	8
2 Normative references.....	8
3 Terms and definitions	9
4 Requirements	9
5 Device Data eXchange format (DDX) file goals and usage.....	9
6 DDX file format and file format rules	9
6.1 Data validity.....	10
6.2 Character set.....	10
6.3 SYNTAX RULES.....	10
7 DDX file content.....	11
7.1 DDX file content rules.....	11
7.1.1 Block structure.....	11
7.1.2 Parameter types	11
7.1.3 Data types	11
7.1.4 Forward references.....	12
7.1.5 Units.....	12
7.1.6 Co-ordinate data	12
7.1.7 Reserved words	12
7.2 DDX DEVICE block syntax.....	13
7.3 DDX data syntax.....	14
8 Definitions of DEVICE block parameters	14
8.1 BLOCK DATA	15
8.1.1 DEVICE_NAME Parameter	15
8.1.2 DEVICE_FORM Parameter	16
8.1.3 BLOCK_VERSION Parameter	16
8.1.4 BLOCK_CREATION_DATE Parameter	16
8.1.5 VERSION Parameter	16
8.2 DEVICE DATA.....	16
8.2.1 DIE_NAME Parameter	16
8.2.2 DIE_PACKAGED_PART_NAME Parameter	16
8.2.3 DIE_MASK_REVISION Parameter	17
8.2.4 MANUFACTURER Parameter	17
8.2.5 DATA_SOURCE Parameter	17
8.2.6 DATA_VERSION Parameter	17
8.2.7 FUNCTION Parameter	17
8.2.8 IC_TECHNOLOGY Parameter.....	18
8.2.9 DEVICE_PICTURE_FILE Parameter	18
8.2.10 DEVICE_DATA_FILE Parameter	18
8.3 GEOMETRIC DATA.....	19
8.3.1 GEOMETRIC_UNITS Parameter	19
8.3.2 GEOMETRIC_VIEW Parameter	19
8.3.3 GEOMETRIC_ORIGIN Parameter	19
8.3.4 SIZE Parameter	20
8.3.5 SIZE_TOLERANCE Parameter.....	20

8.3.6	THICKNESS Parameter	21
8.3.7	THICKNESS_TOLERANCE Parameter	21
8.3.8	FIDUCIAL_TYPE Parameter	21
8.3.9	FIDUCIAL Parameter	23
8.4	TERMINAL DATA	24
8.4.1	TERMINAL_COUNT Parameter	24
8.4.2	TERMINAL_TYPE_COUNT Parameter	24
8.4.3	CONNECTION_COUNT Parameter	24
8.4.4	TERMINAL_TYPE Parameter	25
8.4.5	TERMINAL Parameter	26
8.4.6	TERMINAL_GROUP Parameter	29
8.4.7	PERMUTABLE Parameter	31
8.5	MATERIAL DATA	32
8.5.1	TERMINAL_MATERIAL Parameter	32
8.5.2	TERMINAL_MATERIAL_STRUCTURE Parameter	32
8.5.3	DIE_SEMICONDUCTOR_MATERIAL Parameter	32
8.5.4	DIE_SUBSTRATE_MATERIAL Parameter	33
8.5.5	DIE_SUBSTRATE_CONNECTION Parameter	33
8.5.6	DIE_PASSIVATION_MATERIAL Parameter	33
8.5.7	DIE_BACK_DETAIL Parameter	34
8.6	ELECTRICAL AND THERMAL RATING DATA	34
8.6.1	MAX_TEMP Parameter	34
8.6.2	MAX_TEMP_TIME Parameter	34
8.6.3	POWER_RANGE Parameter	34
8.6.4	TEMPERATURE_RANGE Parameter	34
8.7	SIMULATION DATA	35
8.7.1	Simulator MODEL FILE Parameter	35
8.7.2	Simulator MODEL FILE DATE Parameter	35
8.7.3	Simulator NAME Parameter	35
8.7.4	Simulator VERSION Parameter	35
8.7.5	Simulator COMPLIANCE Parameter	36
8.7.6	Simulator TERM_GROUP Parameter	36
8.8	HANDLING, PACKING, STORAGE and ASSEMBLY DATA	36
8.8.1	DELIVERY_FORM Parameter	36
8.8.2	PACKING_CODE Parameter	36
8.8.3	ASSEMBLY Parameters	36
8.9	WAFER SPECIFIC DATA	37
8.9.1	WAFER_SIZE Parameter	37
8.9.2	WAFER_THICKNESS Parameter	37
8.9.3	WAFER_THICKNESS_TOLERANCE Parameter	37
8.9.4	WAFER_DIE_STEP_SIZE Parameter	38
8.9.5	WAFER_GROSS_DIE_COUNT Parameter	38
8.9.6	WAFER_INDEX Parameter	38
8.9.7	WAFER_RETICULE_STEP_SIZE Parameter	38
8.9.8	WAFER_RETICULE_GROSS_DIE_COUNT Parameter	39
8.9.9	WAFER_INK Parameters	39
8.10	BUMP TERMINATION SPECIFIC DATA	39
8.10.1	BUMP_MATERIAL Parameter	39

8.10.2	BUMP_HEIGHT Parameter	40
8.10.3	BUMP_HEIGHT_TOLERANCE Parameter	40
8.10.4	BUMP_SHAPE Parameter	40
8.10.5	BUMP_SIZE Parameter	40
8.10.6	BUMP_SPECIFICATION_DRAWING Parameter	41
8.10.7	BUMP_ATTACHMENT_METHOD Parameter	41
8.11	MINIMALLY PACKAGED DEVICE (MPD) SPECIFIC DATA	41
8.11.1	MPD_PACKAGE_MATERIAL Parameter	41
8.11.2	MPD_PACKAGE_STYLE Parameter	41
8.11.3	MPD_CONNECTION_TYPE Parameter	42
8.11.4	MPD_MSL_LEVEL Parameter	42
8.11.5	MPD_PACKAGE_DRAWING Parameter	42
8.12	QUALITY, RELIABILITY and TEST DATA	42
8.12.1	QUALITY Parameters	42
8.12.2	TEST Parameters	43
8.13	OTHER DATA	43
8.13.1	TEXT Parameters	43
8.14	CONTROL DATA	43
8.14.1	PARSE Parameters	43
Annex A (informative)	An example of a DDX DEVICE block	47
Annex B (informative)	Groups and Permutation	49
Annex C (informative)	A Typical CAD view from the DDX file block example given in Annex A	52
Annex D (informative)	Properties for Simulation	53
Annex E (informative)	TERMINAL and TERMINAL_TYPE graphical usage for CAD/CAM systems	55
Annex F (informative)	Cross-reference with IEC 61360-4	58
Annex G (informative)	Notes on VERSION and NAME parameters	61
Annex H (informative)	Notes on WAFER parameters	62
Annex I (informative)	Additional notes	64
Annex J (informative)	DDX Version history	65
Annex K (informative)	Parse Control	68
Figure 1	– Relationship between geometric centre and geometric origin	20
Figure C.1	– CAD representation of DDX example from Annex A	52
Figure E.1	– Highlighting the MX and MY orientation properties	56
Figure E.2	– Highlighting the angular rotational orientation properties	57
Figure H.1	– Illustrating the WAFER parameters	63
Table 1	– Terminal shape types	25
Table 2	– Terminal shape co-ordinates	26
Table 3	– Terminal IO types	28
Table 4	– Substrate Connection Parameters	33
Table F.1	– Parameter List	58
Table J.1	– Parameter Change History List	65

INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DIE PRODUCTS –

Part 2: Exchange data formats

FOREWORD

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International Standard IEC 62258-2 has been prepared by IEC technical committee 47: Semiconductor devices.

This standard shall be read in conjunction with IEC 62258-1.

This second edition cancels and replaces the first edition published in 2005, and constitutes a technical revision.

With respect to the first edition, the following parameters have been updated for this edition:

Subclause	Parameter name
8.2.9	DEVICE_PICTURE_FILE
8.2.10	DEVICE_DATA_FILE
8.4.6	TERMINAL_GROUP
8.4.7	PERMUTABLE
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8.11.5	MPD_PACKAGE_DRAWING
8.12.1	QUALITY
8.12.2	TEST
8.13.1	TEXT
8.14.1	PARSE

The text of this standard is based on the following documents:

FDIS	Report on voting
47/2085/FDIS	47/2095/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

INTRODUCTION

This International Standard is based on the work carried out in the ESPRIT 4th Framework project GOODDIE which resulted in publication of the ES 59008 series of European specifications. Organisations that helped prepare this document include the ESPRIT ENCAST and ENCASIT projects, the Die Products Consortium, JEITA, JEDEC and ZVEI.

The structure of this International Standard as currently conceived is as follows:

Under main title: IEC 62258: Semiconductor die products

- Part 1: Procurement and use
- Part 2: Exchange data formats
- Part 3: Recommendations for good practice in handling, packing and storage (Technical report)
- Part 4: Questionnaire for die users and suppliers (Technical report)
- Part 5: Requirements for information concerning electrical simulation
- Part 6: Requirements for information concerning thermal simulation
- Part 7: XML schema for data exchange (Technical report)
- Part 8: EXPRESS model schema for data exchange (Technical report)

Further parts may be added as required.

SEMICONDUCTOR DIE PRODUCTS –

Part 2: Exchange data formats

1 Scope and object

This Part of IEC 62258 specifies the data formats that may be used for the exchange of data which is covered by other parts of the IEC 62258 series, as well as definitions of all parameters used according to the principles and methods of IEC 61360. It introduces a Device Data Exchange (DDX) format, with the prime goal of facilitating the transfer of adequate geometric data between die manufacturer and CAD/CAE user and formal information models that allow data exchange in other formats such as STEP physical file format, in accordance with ISO 10303-21, and XML. The data format has been kept intentionally flexible to permit usage beyond this initial scope.

It has been developed to facilitate the production, supply and use of semiconductor die products, including but not limited to:

- wafers,
- singulated bare die,
- die and wafers with attached connection structures,
- minimally or partially encapsulated die and wafers.

This standard reflects the DDX data format at version **1.3.0**

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 62258-1, *Semiconductor die products – Part 1: Procurement and use*

IEC 61360-4:2005, *Standard data element types with associated classification scheme for electric components – Part 4: IEC reference collection of standard data element types, component classes* 303-21

ISO 8601:2004, *Data elements and interchange formats – Information interchange – Representation of dates and times*

ISO 6093:1985, *Information processing – Representation of numerical values in character strings for information interchange*

IPC/JEDEC J-STD-033B:2007, *Handling, Packing, Shipping and Use of Moisture/Reflow Sensitive Surface Mount Devices*

ISO 10303-21:2002, *Industrial automation systems and integration – Product data representation and exchange – Part 21: Implementation methods: Clear text encoding of the exchange structure*

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